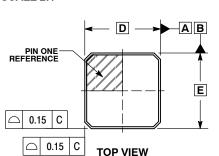


## **QFN32 5x5, 0.5P (PUNCHED)**

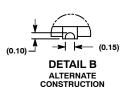
CASE 485CZ **ISSUE A** 

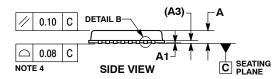
**DATE 29 JUL 2013** 

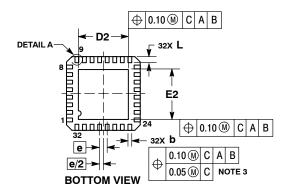




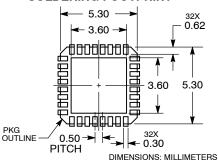
ALTERNATE TERMINAL CONSTRUCTIONS







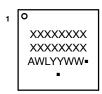
## **RECOMMENDED SOLDERING FOOTPRINT**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  CONTROLLING DIMENSIONS: MILLIMETERS.
  DIMENSION b APPLIES TO PLATED
  TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	0.90	
A1		0.05	
A3	0.20 REF		
b	0.20	0.30	
D	5.00 BSC		
D2	3.20	3.40	
E	5.00 BSC		
E2	3.20	3.40	
е	0.50 BSC		
L	0.30	0.50	

## **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code

= Assembly Location Α WL = Wafer Lot

YY = Year WW = Work Week G = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	QFN32 5x5, 0.5P (PUNCHED)		PAGE 1 OF 1

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